ISSOCIATION ( LECTRONICS	© Copyright 2005.	Material Composition Declaration  Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both enternational and Pan-American copyright conventions.		nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
52-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier ]	Information													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
semi											2024-05-17			
ontact Nai	me	Title - Contact			I	Phone - Contact*				Email - Contact*				
roduct-En	nv-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized	Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
roduct-En	nv-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Veight*	UOM	Unit Type
	FGH75T65UPD-F085 FS1 T TO247		FS1 T TO247 75A	TO247 75A 650V AUTO		2024-05-17 CPA		PA PA	5	456.725	mg	Each		
	turing Process Informa		F	A11	CTD 020 MCI	Datina	Deals Deals	D. J. T.		Mary Times at Deale	Townson	North of	a of Doflary Cou	1
8				-STD-020 MSL	_ Rating		cess Body Temperature   Max Time at Peak   C   30		1 1		r of Reflow Cyc	eles		
	Matte Tin (Sn) - annealed		CU Alloy	N	NA		0		C	30	second	ls 3		
omments														
	nformation regarding materia	1	1	2										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not on the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence o										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	32.0	mg	Supplier	Silicon (Si)	7440-21-3		32	mg
Die Attach Solder	35.025	mg	Supplier	Silver (Ag)	7440-22-4		0.8756	mg
			A	Lead (Pb)	7439-92-1	7a	32.3981	mg
			Supplier	Tin (Sn)	7440-31-5		1.7512	mg
Lead Frame	3612.9	mg	Supplier	Zinc (Zn)	7440-66-6		1.75	mg
			В	Nickel (Ni)	7440-02-0		117.9998	mg
			Supplier	Iron (Fe)	7439-89-6		2.1	mg
			Supplier	Copper (Cu)	7440-50-8		3489.9998	mg
			Supplier	Phosphorus (P)	7723-14-0		1.05	mg
Mold Compound-Black	1739.8	mg	Supplier	Brominated Epoxy Resin-2	68541-56-0		43.495	mg
			Supplier	Other Epoxy resins	Proprietary Data		52.194	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		34.796	mg
			Supplier	Carbon Black (C)	1333-86-4		8.699	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1513.6261	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		86.99	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg